

ADM-XRC-6TL

XMC Mezzanine Card

User Guide

Version 1.0



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1. Introduction

The ADM-XRC-6TL is a high-performance XMC for applications using Virtex-6 FPGAs from Xilinx. This card supports all Virtex-6 LXT and SXT devices available in the FF(G)1759 package.

The card includes separate FPGA with a PCIe bridge developed by Alpha Data. Using a separate device allows high performance operation without the need to integrate proprietary cores in the user (target) FPGA.

The ADM-XRC-6TL is available in air-cooled and conduction-cooled configurations.

1.1. Key Features

- Single-width XMC, compliant to VITA Standard 42.0 and 42.3,
- Dedicated 4-lane PCI-Express interface with high-performance DMA controllers,
- Virtex-6 FPGA in FF(G)1759 package,
- 4 independent banks of DDR3-800 SDRAM, 256MB/bank, 1GB total (2GB option),
- Front-panel (XRM) interface with adjustable voltage, 146 free I/O signals and 8 MGT links to user FPGA,
- Rear-panel (XMC) interface with 24 GPIO signals & 8 GTP links between user FPGA and P6,
- 4 additional GTP links between user FPGA and P5,
- Rear-panel (PMC) interface with 32 GPIO signals between user FPGA and P4 (optional)
- Voltage and temperature monitoring

1.2. References & Specifications

ANSI/VITA 42.0	<i>XMC Standard</i> , December 2008, VITA, ISBN 1-885731-49-3
ANSI/VITA 42.3	<i>XMC PCI Express Protocol Layer Standard</i> , June 2006, VITA, ISBN 1-885731-43-4
ANSI/IEEE 1386-2001	<i>IEEE Standard for a Common Mezzanine Card (CMC) Family</i> , October 2001, IEEE, ISBN 0-7381-2829-5
ANSI/IEEE 1386.1-2001	<i>IEEE Standard Physical and Environmental Layers for PCI Mezzanine Cards (PMC)</i> , October 2001, IEEE, ISBN 0-7381-2831-7
ANSI/VITA 20-2001 (R2005)	<i>Conduction Cooled PMC</i> , February 2005, VITA, ISBN 1-885731-26-4

Table 1.1: References

2. Installation

2.1. Software Installation

Please refer to the Software Development Kit (SDK) installation CD. The SDK contains drivers, examples for host control and FPGA design and comprehensive help on application interfacing.

2.2. Hardware Installation

2.2.1. Handling Instructions



The components on this board can be damaged by electrostatic discharge (ESD).

To prevent damage, observe SSD precautions:

- Always wear a wrist-strap when handling the card
- Hold the board by the edges
- Avoid touching any components
- Store in ESD safe bag.

2.2.2. Motherboard / Carrier Requirements

The ADM-XRC-6TL is a single width XMC.3 mezzanine with optional P6 and P4 connectors.

The motherboard/ carrier must comply with the XMC.3 (VITA 42.3) specification for the Primary XMC connector, J5. The Secondary XMC connector, J6 should also be compatible with the XMC.3 pinout.

Note: Connector P6 on the card is not compatible with the XMC.10 (GPIO) Standard. In particular, USB VCC must not be applied on this connector.

The ADM-XRC-6TL is compatible with either 5V or 12V on the “VPWR” power rail.

The power dissipation of the board is highly dependent on the Target FPGA application. A power estimator spreadsheet is available on request from Alpha Data. This should be used in conjunction with Xilinx power estimation tools to determine the exact current requirements for each power rail.

2.2.3. Cooling Requirements

t.b.d.

3. Functional Description

3.1. Overview

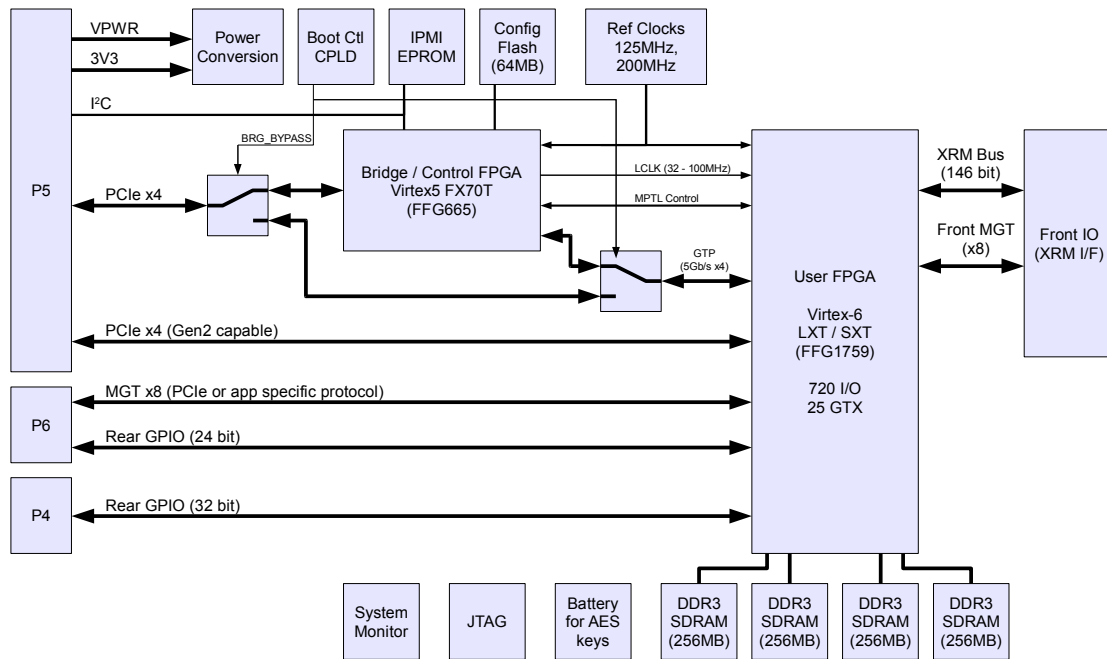


Figure 1: ADM-XRC-6TL, Top-Level Block Diagram

3.1.1. Switch Definitions

There is a set of eight DIP switches placed on the rear of the board. Their functions are described in Table 3.1 below.

Note: All switches are OFF by default. All *Factory Test* and *Reserved* switches must be in the OFF position for normal operation.

Switch Ref.	Function	ON State	Off State
SW1-1	Bridge Bypass	Bridge FPGA is bypassed – PCIe lanes (3:0) are connected directly to the user FPGA.	Bridge FPGA is used. PCIe lanes (3:0) are connected to the bridge.
SW1-2	<i>Factory Test</i>	Factory Test Mode	Normal Operation
SW1-3	<i>Reserved</i>	-	-
SW1-4	<i>Reserved</i>	-	-
SW1-5	One-time Configuration	Target FPGA is cleared then configured from Flash at power-up only.	Target FPGA is cleared then configured from flash at power-up and after every board reset (MRSTI#).
SW1-6	Flash Boot Inhibit	Target FPGA is not configured from on-board flash memory.	Target FPGA is configured from on-board flash memory.
SW1-7	<i>Reserved</i>	-	-
SW1-8	<i>Reserved</i>	-	-

Table 3.1: Switch Definitions

3.1.2. LED Definitions

There are six LEDs placed on the rear of the board to indicate the current status:

Comp. Ref.	Function	ON State	Off State
D7 (Amber)	MVMRO	Inhibit writes to non-volatile memories	Enable writes to non-volatile memories.
D8 (Amber)	Bridge Bypass	Bridge FPGA is bypassed – PCIe lanes (3:0) are connected directly to the user FPGA	Bridge FPGA is used. PCIe lanes (3:0) are connected to the bridge.
D11 (Green)	Power Good	2.5V, 1.8V and 1.5V power supplies are on.	2.5V, 1.8V and 1.5V power supplies are not all on or at their correct levels.
D12 (Green)	Bridge Done	Bridge FPGA is configured	Bridge FPGA is unconfigured
D13 (Green)	Target Done	Target FPGA is configured	Target FPGA is unconfigured
D14 (Red)	Fault	Voltage or Temperature Fault Detected.	No fault detected

Table 3.2: LED Definitions

3.2. XMC Platform Interface

3.2.1. IPMI I²C

A 2 kbit I²C EEPROM (type M24C02) is connected to the XMC IPMI. This memory contains board information (type, voltage requirements etc.) as defined in the the XMC based specification.

3.2.2. MBIST#

Built-In Self Test. This output signal is driven active (low) until the FPGA with PCIe interface is configured. In normal operation, this is the bridge FPGA. In Bridge Bypass mode, it is the target FPGA.

3.2.3. MVMRO

XMC Write Prohibit. This signal is an input from the carrier. When asserted (high), all writes to non-volatile memories are inhibited. This is indicated by the Amber LED, D7.

This signal cannot be internally driven or over-ridden. A buffered version of the signal is connected to the target FPGA at pin AD30.

3.2.4. MRSTI#

XMC Reset In. This signal is an active low input from the carrier. When asserted, the bridge FPGA will be reset. At the end of the reset, the target FPGA configuration sequence will start. (See Section 3.5 on page 15.)

The MRSTI# signal is translated to 2.5V levels and connected to the target FPGA at pin AC30.

3.2.5. MRSTO#

XMC Reset Out. This optional output signal is unused and undriven.

3.2.6. MPRESENT#

Module Present. This output signal is connected directly to 0V.

3.2.7. JTAG Interface

The JTAG interface on the XMC connector is unused. XMC_TDI is connected directly to XMC_TDO.

A JTAG boundary scan chain is connected to header J2. This allows the connection of the Xilinx JTAG cable for FPGA debug using the Xilinx ChipScope tools.

The JTAG Header pinout is shown in Figure 1 below:

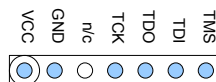


Figure 2: JTAG Header, J2

The scan chain is shown in Figure 3:

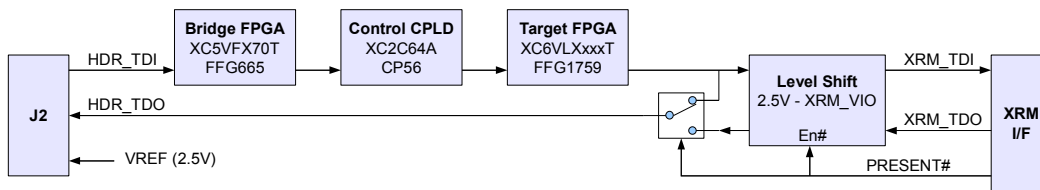


Figure 3: JTAG Boundary Scan Chain

3.2.7.1. JTAG Voltage

The Vcc supply provided on J2 to the JTAG cable is +2.5V and is protected by a poly fuse rated at 350mA. The JTAG scan chain uses 2.5V CMOS levels at J2. 3.3V signals must not be used. The JTAG signals at the XRM interface use the adjustable voltage XRM_VIO.

3.3. Clocks

The ADM-XRC-6TL provides a wide variety of clocking options. The programmable and fixed reference clocks on the board can be combined with the PLLs in the FPGA to suit the target application.

The on-board clocks are detailed below.

Note: Clock Termination

The LVDS clocks do not have termination resistors on the circuit board. On-die terminations in the FPGA must be enabled by setting the attribute "DIFF_TERM = TRUE". This can either be set in the source code when instantiating the buffer, or in the User Constraints File (UCF). See the Xilinx Virtex-6 Libraries Guide and Constraints Guide for further details.

3.3.1. LCLK

The programmable clock "LCLK" is a single-ended clock with LVCMOS25 levels, connected to a Global Clock input on the Target FPGA at pin AY14. It is generated from a 100MHz reference by a DCM within the bridge FPGA. LCLK may be set between 32MHz and 140MHz.

Signal	Target FPGA Input	IO Standard	"P" pin	"N" pin
LCLK	IO_L0P_GC_34	LVCMOS25	AY14	n/a

Table 3.3: LCLK Connection

The frequency is set by writing DCM multiply and divide values to the LCLOCK register in the bridge FPGA.

The default LCLK rate is 40MHz and is set at power-up. An alternative default rate can be stored in flash memory:

FlashAdr 0x0100_0400 = DCM Multiplier Value -1

FlashAdr 0x0100_0402 = DCM Divider Value -1

Note: If the target FPGA design includes a DCM driven by LCLK, the clock frequency should be set prior to Target FPGA configuration.

3.3.2. REFCLK200M

The fixed 200MHz reference clock REFCLK200M is a differential clock signal using LVDS. It is connected to a Global Clock input on the Target FPGA at pins AP11 and AP12.

This clock can be used to generate application-specific clock frequencies using the PLLs within the Virtex-6 FPGA. It is also suitable as the reference clock for the IO delay control block (IDELAYCTRL).

Signal	Target FPGA Input	IO Standard	“P” pin	“N” pin
REFCLK200M	IO_L1_GC_34	LVDS_25	AP11	AP12

Table 3.4: REFCLK200M Connections

3.3.3. PCIe Reference Clock (PCIEREFCLK)

The 100MHz PCI Express reference clock is provided by the carrier card through the Primary XMC connector, P5 at pins A19 and B19. This is multiplied to 250MHz and distributed to both the Bridge and Target FPGAs. On the Target FPGA, it is connected to GTX Quad 113 and 114 to allow its use as a reference for all the MGT links to the XMC connectors. (See Figure 5 on page 18 for details of the MGT links and reference clocks.)

Signal	Target FPGA Input	IO Standard	“P” pin	“N” pin
PCIEREFCLK_1	MGTREFCLK1_113	LVDS_25	AD8	AD7
PCIEREFCLK_2	MGTREFCLK0_114	LVDS_25	AB8	AB7

Table 3.5: PCIEREFCLK Connections

3.3.4. Secondary XMC (P6) Reference Clock (P6REFCLK)

The carrier can provide a reference clock through the Secondary XMC connector, P6, at pins A19 & B19. This “P6REFCLK” is connected directly to the target FPGA.

Signal	Target FPGA Input	IO Standard	“P” pin	“N” pin
P6REFCLK	MGTREFCLK0_113	carrier dependent	AF8	AF7

Table 3.6: P6REFCLK Connections

3.3.5. REFCLK125M

The fixed 125.0MHz reference clock REFCLK125M, is a differential clock signal using LVDS. The clock is buffered and connected to three MGTREFCLK0 inputs on the Target FPGA at GTX Quad 112, 115 and 116. (See Figure 5.)

Signal	Target FPGA Input	IO Standard	“P” pin	“N” pin
REFCLK125M_3	MGTREFCLK0_112	LVDS_25	AK8	AK7
REFCLK125M_2	MGTREFCLK0_115	LVDS_25	V8	V7
REFCLK125M_1	MGTREFCLK0_116	LVDS_25	M8	M7

Table 3.7: REFCLK125M Connections

3.3.6. GCLK_M2C

The clock “GCLK_M2C” is a differential clock signal using LVDS. It is provided by an XRM module through the XRM connector, CN1, at pins 110 & 108. It is connected to a Global Clock input on the Target FPGA.

Signal	Target FPGA Input	IO Standard	“P” pin	“N” pin
GCLK_M2C	IO_L0_GC_24	LVDS_25	AE30	AF30

Table 3.8: GCLK_M2C Connections

3.3.7. MGTCLK_M2C

The reference clock “MGTCLK_M2C” is a differential clock signal using LVDS. The clock is provided by an XRM module through the XRM connector, CN1, at pins 109 & 111. It is connected to GTX Quad 117 on the Target FPGA for application specific frequencies / line rates.

Signal	Target FPGA Input	IO Standard	“P” pin	“N” pin
MGTCLK_M2C	MGTREFCLK0_117	LVDS_25	G10	G9

Table 3.9: MGTCLK_M2C Connections

3.4. Flash Memory

A 512Mb Flash Memory (Intel / Numonyx PC48F4400P0VB00) is used to store board Vital Product Data (VPD), programmable clock parameters and configuration bitstreams for the Bridge and Target FPGAs.

The flash memory cannot be accessed by the target FPGA. Host access is only possible through the FLCTL, FLPAGE and FLDATA registers in the bridge FPGA.

Utilities for erasing, programming and verification of the flash memory are provided in the ADM-XRC SDK.

Write Protect

The Flash Write Protect (WP#) pin is connected to an inverted version of the MVMRO signal at the XMC interface. When the MVMRO signal is active (High), all writes to the flash will be inhibited. This state will be indicated by the Amber LED, D7.

Alternate Bridge FPGA Bitstream		0x0000_0000
		0x007F_FFFE
Default Bridge FPGA Bitstream		0x0080_0000
		0x00FF_FFFE
Vital Product Data (VPD)		0x0100_0000
		0x0100_03FE
LCLK Word (15:0)		0x0100_0400
LCLK Word (31:16)		0x0100_0402
reserved		
B0 Length(7:0)	Boot Flag 0	0x0120_0000
Bitstream 0 Length(23:8)		0x0120_0002
reserved		
Default Target FPGA Bitstream (Target Bitstream 0)		0x0122_0000
		0x028F_FFFE
B1 Length(7:0)	Boot Flag 1	0x0290_0000
Bitstream 1 Length(23:8)		0x0290_0002
reserved		
Alternate Target FPGA Bitstream (Target Bitstream 1)		0x0292_0000
		0x03FF_FFFE

Figure 4: Flash Memory Map

3.5. Configuration

3.5.1. Power-Up Sequence

If valid data is stored in the flash memory, the bridge will automatically set the programmable clock generator and configure the Target FPGA at power-up.

This sequence can be inhibited by turning the Flash Boot Inhibit (FBI) switch, SW1-6 to ON. (See Table 3.1).

Note

If an over-temperature alert is detected from the System Monitor, the target will be cleared by pulsing its PROG signal. See Section 3.6.1.

3.6. Health Monitoring

The ADM-XRC-6TL has the ability to monitor temperature and voltage to maintain a check on the operation of the board. The monitoring is implemented using a National Semiconductor LM87 connected to control logic in the bridge FPGA using I²C.

The control logic scans the LM87 when instructed by host software and stores the current measurements in a blockram. This allows the values to be read without the need to communicate directly with the LM87.

The following voltage rails and temperatures are monitored:

Monitor	Purpose
1.0V	FPGA Core Supply (VccINT)
1.5V	DDR3 SDRAM, Target FPGA memory I/O
1.8V	Flash Memory, DC-DC converters for GTX Supplies
2.5V	FPGA Auxilliary Supply (VccAUX)
XRM_VIO	XRM (Front-Panel) I/O voltage
3.3V	Board Input Supply
5.0V	Internally generated 5V supply
VPWR	Board Input Supply (either 5.0V or 12.0V)
Temp1	Target FPGA on-die temperature
Temp2	LM87 on-die temperature

Table 3.10: Voltage and Temperature Monitors

An example application that reads the system monitor (“sysmon”) is available on request.

3.6.1. Automatic Temperature Monitoring

At power-up, the control logic sets temperature limits and enables the over-temperature interrupt in the LM87. If the One-Time Configuration OTC function is disabled (using SW1-5, see Table 3.1), the limits and interrupt will be re-set after a board reset (MRSTI#). If OTC is enabled, the limits and interrupt will only be set once at power-up.

The temperature limits are shown in Table 3.11 below:

	Target FPGA		Board (LM87)	
	Min	Max	Min	Max
Commercial	0 °C	+85 °C	0 °C	+70 °C
Industrial	-40 °C	+100 °C	-40 °C	+85 °C

Table 3.11: Temperature Limits

Important:

If any temperature limit is exceeded, the Target FPGA is automatically cleared. This is indicated by Green LED D13 (Target DONE) switching off and Red LED, D14 (Fault) switching on.

The purpose of this mechanism is to protect the card from damage due to over-temperature. It is possible that it will cause the user application and, possibly, the host computer to “hang”.

3.7. Local Bus

A Multiplexed Packet Transport Link (MPTL) connects the Bridge and Target FPGAs. It is capable of transferring data at up to 1GB/s simultaneously in each direction.

The MPTL replaces the parallel local bus used in previous generations of the ADM-XRC series.

Details of the link and example designs are given in the Software Development Kit (SDK).

3.8. Target FPGA

3.8.1. I/O Bank Voltages

The Target FPGA IO is arranged in banks, each with their own supply pins. The bank numbers, their voltage and function are shown in Table 3.12. Full details of the IOSTANDARD required for each signal are given in the SDK.

IO Banks	Voltage	Purpose
0, 24	2.5V	Configuration, JTAG, Pn4
33,34,35	2.5V	Pn4, Local Link, LCLK, REFCLK200M, reserved pins
37, 36, 27, 26, 25	1.5V	DRAM Banks 0 & 1
13, 12, 23, 32, 22	1.5V	DRAM Banks 2 & 3
14, 15, 16, 17	XRM_VIO	XRM Interface (variable voltage)
21, 28, 38	1.5V	<i>reserved</i>

Table 3.12: Target FPGA IO Banks

3.8.2. GTX Mappings

There are a total of 24 MGT links connected to the Target FPGA:

- 4 to the Bridge FPGA (or PCIe (3:0))
- 4 to PCIe(7:4)
- 8 to the XRM Interface
- 8 to the secondary XMC connector (P6)

The connections of these links and their associated reference clocks are shown in Figure 5 below:

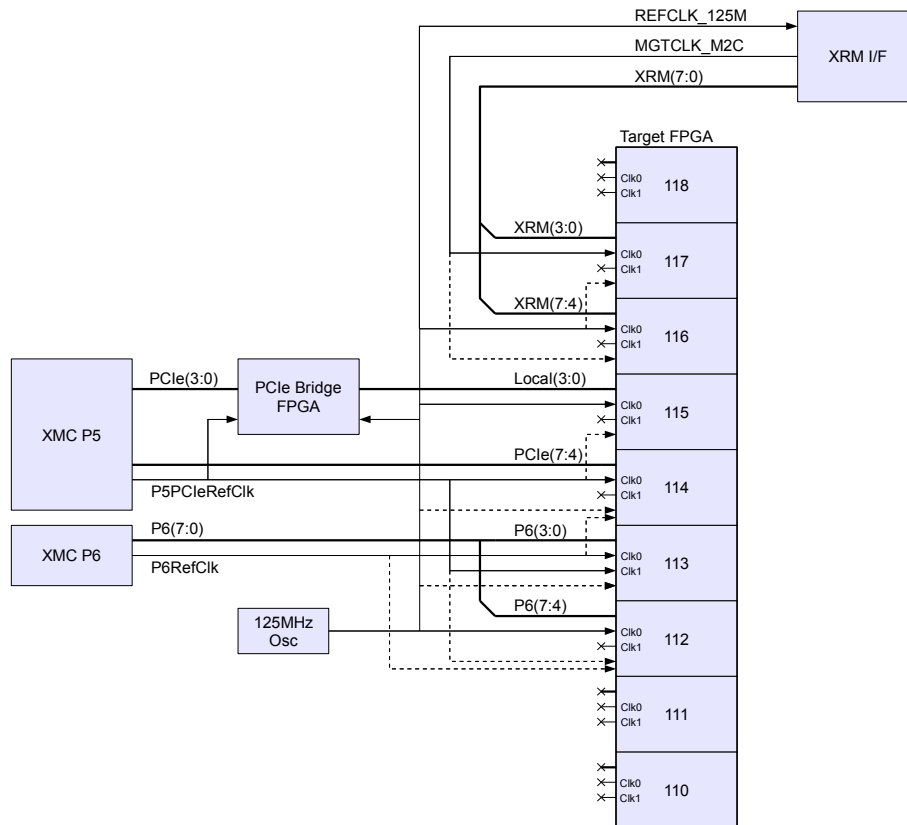


Figure 5: MGT Links & Clocking

Notes:

- (1) The numbering in the Target FPGA refers to the GTX Quad number. Each Quad contains a grouping of four *GTXE1* Multi-Gigabit Transceivers and two dedicated reference clock pairs.
- (2) Reference clocks can be routed internally from one Quad to other Quads directly above and below. In the diagram, clocks shown with a dashed line are available for use by the Quad using this internal routing.

3.9. Memory Interfaces

The ADM-XRC-6TL has four independent banks of DDR3 SDRAM. Each bank consists of two 16 bit wide memory devices in parallel to provide a 32 bit datapath capable of running up to 400MHz (DDR-800). 1Gb devices (Micron MT41J64M16-187E) are fitted as standard to provide 256MB per bank. 2Gb devices (giving 512MB per bank) are available as an ordering option.

The memory banks are arranged for compatibility with the Xilinx Memory Interface Generator (MIG). Figure 6 Shows the component references and FPGA banks used. Full details of the interface, signalling standards and an example design are provided in the SDK.

Note:

DRAM Banks 0 & 1 must use a common write clock due to restrictions in CLKPERF routing in the FPGA.

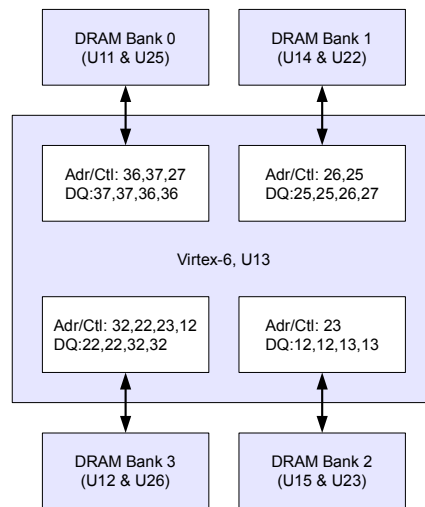


Figure 6: DRAM Banks

3.10. XRM Interface and Front-Panel I/O

The XRM interface provides a high-performance and flexible front-panel interface through a range of interchangeable XRM modules. Further details of the XRM modules can be found on the Alpha Data website.

The XRM interface consists of two samtec connectors, CN1 and J3.

3.10.1. XRM Connector, CN1

Connector CN1 is for general-purpose signals, power and module control. The connector is a 180-way Samtec connector with 3 fields.

The part fitted to the ADM-XRC-6TL is Samtec QSH-090-01-F-D-A-K.

Full pinout information for this connector is listed in Appendix B.1 - B.3.

3.10.2. XRM Connector J3

Connector J3 is for the high-speed serial (MGT) links.

The part fitted to the ADM-XRC-6TL is Samtec QSE-014-01-F-D-DP-A-K.

Full pinout information for this connector is listed in Appendix B.4.

3.10.3. XRM I/F – GPIO

The general purpose IO (GPIO) signals are connected in 4 groups to the Target FPGA. Each group consists of 16 standard I/O pairs, a Regional Clock Capable pair and either 2 or 4 single-ended signals. There are no on-board terminations on the pairs and any can be used in single-ended modes.

To allow fast data transfer, all of the GPIO signals within a group are delay matched to within 100ps.

All the XRM GPIO signals and FPGA IO banks share a common voltage, XRM_VIO, that can be either 2.5V, 1.8V or 1.5V. The required voltage is stored within the platform management PROM on the XRM.

Group	FPGA Bank	Name	Function
Group A	17	XRM_DA (15:0)	16 diff. Pairs / 32 single-ended
		XRM_DA_CC (16)	Regional Clock / GPIO pair / 2 single-ended
		SA (1:0)	2 single-ended GPIO
Group B	16	XRM_DB (15:0)	16 diff. Pairs / 32 single-ended
		XRM_DB_CC (16)	Regional Clock / GPIO pair / 2 single-ended
		SB (1:0)	2 single-ended GPIO
Group C	15	XRM_DC (15:0)	16 diff. Pairs / 32 single-ended
		XRM_DC_CC (16)	Regional Clock / GPIO pair / 2 single-ended
		SC (1:0)	2 single-ended GPIO
Group D	14	XRM_DD (15:0)	16 diff. Pairs / 32 single-ended
		XRM_DD_CC (16)	Regional Clock / GPIO pair / 2 single-ended
		SD (3:0)	4 single-ended GPIO

Table 3.13: XRM GPIO Groups

3.10.4. XRM I/F – High-speed Serial Links

Eight MGT links are routed between the Target FPGA and the XRM interface. Lanes (6:0) are routed through the Samtec QSE-DP connector, J3. Lane (7) is routed through the Samtec QSH connector, CN1.

Appendix A. Rear Connector Pinouts

A.1. Primary XMC Connector, P5

	A	B	C	D	E	F
1	PET0p0	PET0n0	3.3V	PET0p1	PET0n1	VPWR ⁽⁵⁾
2	GND	GND	XMC_TRST#	GND	GND	MRSTI#
3	PET0p2	PET0n2	3.3V	PET0p3	PET0n3	VPWR ⁽⁵⁾
4	GND	GND	XMC_TCK	GND	GND	MRSTO#
5	PET0p4	PET0n4	3.3V	PET0p5	PET0n5	VPWR ⁽⁵⁾
6	GND	GND	XMC_TMS	GND	GND	+12V
7	PET0p6	PET0n6	3.3V	PET0p7	PET0n7	VPWR ⁽⁵⁾
8	GND	GND	XMC_TDI ⁽³⁾	GND	GND	-12V
9	-	-	-	-	-	VPWR ⁽⁵⁾
10	GND	GND	XMC_TDO ⁽³⁾	GND	GND	GA0
11	PER0p0	PER0n0	MBIST#	PER0p1	PER0n1	VPWR ⁽⁵⁾
12	GND	GND	GA1	GND	GND	MPRESENT#
13	PER0p2	PER0n2	- ⁽⁴⁾	PER0p3	PER0n3	VPWR ⁽⁵⁾
14	GND	GND	GA2	GND	GND	MSDA
15	PER0p4	PER0n4	-	PER0p5	PER0n5	VPWR ⁽⁵⁾
16	GND	GND	MVMRO	GND	GND	MSCL
17	PER0p6	PER0n6	-	PER0p7	PER0n7	-
18	GND	GND	-	GND	GND	-
19	REFCLK+0	REFCLK-0	-	WAKE#	ROOT0#	-

Table A.1: XMC Connector, P5

Notes:

- (1) PCIe Channel 0 Lanes (3:0) are connected to the Bridge FPGA by default but can be routed to the target FPGA.
- (2) PCIe Channel 0 Lanes (7:4) are only connected to the Target FPGA. This may be used as a second, 4-lane channel if supported by the carrier card, although this configuration is non-standard.
- (3) JTAG is unused. XMC_TDI is connected to XMC_TDO.
- (4) 3.3V AUX is unused.
- (5) VPWR can be either +5V or +12V.

A.2. Secondary XMC Connector, P6

	A	B	C	D	E	F
1	PET1p0	PET1n0	GPIO 00	PET1p1	PET1n1	GPIO 12
2	GND	GND	GPIO 01	GND	GND	GPIO 13
3	PET1p2	PET1n2	GPIO 02	PET1p3	PET1n3	GPIO 14
4	GND	GND	GPIO 03	GND	GND	GPIO 15
5	PET1p4	PET1n4	GPIO 04	PET1p5	PET1n5	GPIO 16
6	GND	GND	GPIO 05	GND	GND	GPIO 17
7	PET1p6	PET1n6	GPIO 06	PET1p7	PET1n7	GPIO 18
8	GND	GND	GPIO 07	GND	GND	GPIO 19
9	-	-	GPIO 08	-	-	GPIO 20
10	GND	GND	GPIO 09	GND	GND	GPIO 21
11	PER1p0	PER1n0	GPIO 10	PER1p1	PER1n1	GPIO 22
12	GND	GND	GPIO 11	GND	GND	GPIO 23
13	PER1p2	PER1n2	-	PER1p3	PER1n3	-
14	GND	GND	-	GND	GND	-
15	PER1p4	PER1n4	-	PER1p5	PER1n5	-
16	GND	GND	-	GND	GND	-
17	PER1p6	PER1n6	-	PER1p7	PER1n7	-
18	GND	GND	-	GND	GND	-
19	REFCLK+1	REFCLK-1	-	-	ROOT1#	-

Table A.2: XMC Connector, P6

Notes:

- (1) PCIe Channel 1 Lanes (7:0) are connected to the Target FPGA. Other protocols can be used on these links, subject to carrier support.
- (2) GPIO signals are single-ended and 3.3V compatible.

A.3. PMC Connector, P4

The PMC Connector, P4 is fitted as standard but can be omitted if required.

32 GPIO signals are connected between P4 and the target FPGA via FET bus switches. By limiting the signal voltage at 2.5V, these allow the use of 3.3V or 2.5V signalling levels to be used at P4.

Signals may be used in single-ended or as differential pairs.

Signal	FPGA Pin	P4 Pin	P4 Pin	FPGA Pin	Signal
PN4 P1	N33	1	2	T30	PN4 P2
PN4 N1	P33	3	4	R30	PN4 N2
PN4 P3	R32	5	6	W30	PN4 P4
PN4 N3	T32	7	8	V30	PN4 N4
PN4 P5	V31	9	10	AN14	PN4 P6
PN4 N5	W31	11	12	AN13	PN4 N6
PN4 P7	Y30	13	14	AA31	PN4 P8
PN4 N7	AA30	15	16	AB31	PN4 N8
PN4 P9	AG32	17	18	AH30	PN4 P10
PN4 N9	AF31	19	20	AJ30	PN4 N10
PN4 P11	AH31	21	22	AK33	PN4 P12
PN4 N11	AG31	23	24	AJ32	PN4 N12
PN4 P13	AV13	25	26	AW12	PN4 P14
PN4 N13	AV14	27	28	AW13	PN4 N14
PN4 P15	BA16	29	30	BB13	PN4 P16
PN4 N15	BA17	31	32	BB14	PN4 N16
-	-	33	34	-	-
-	-	35	36	-	-
-	-	37	38	-	-
-	-	39	40	-	-
-	-	41	42	-	-
-	-	43	44	-	-
-	-	45	46	-	-
-	-	47	48	-	-
-	-	49	50	-	-
-	-	51	52	-	-
-	-	53	54	-	-
-	-	55	56	-	-
-	-	57	58	-	-
-	-	59	60	-	-
-	-	61	62	-	-
-	-	63	64	-	-

Table A.3: PMC Connector, P4

Appendix B. Front (XRM) Connector Pinouts

The XRM interface consists of two connectors: CN1 and J3. CN1 is a 180-way Samtec QSH in 3 fields. It is for general-purpose signals, power and module control. J3 is a 28-way Samtec QSE-DP for high-speed serial (MGT) links.

Key:

Power
JTAG & Platform Management
General Purpose I/O
Clocks
MGT Links

B.1. XRM Connector CN1, Field 1

Signal	FPGA	Samtec	Samtec	FPGA	Signal
DA_N0	N39	1	2	M39	DA_N1
DA_P0	N38	3	4	M38	DA_P1
DA_N2	T36	5	6	P40	DA_P3
DA_P2	U36	7	8	P41	DA_N3
DA_N4	L40	9	10	L42	DA_N5
DA_P4	L39	11	12	L41	DA_P5
DA_N6	T35	13	14	R42	DA_N7
DA_P6	T34	15	16	P42	DA_P7
DA_P8	R39	17	18	M41	DA_P9
DA_N8	P38	19	20	M42	DA_N9
DA_N10	P37	21	22	T40	DA_N11
DA_P10	N36	23	24	R40	DA_P11
DA_N12	R38	25	26	N40	DA_P13
DA_P12	T39	27	28	N41	DA_N13
DA_N14	M37	29	30	T41	DA_P15
DA_P14	M36	31	32	T42	DA_N15
DB_N0	Y37	33	34	V36	DB_N1
DB_P0	W37	35	36	W36	DB_P1
SA_0	N35	37	38	P36	DA_CC_P16
3V3	-	39	40	P35	DA_CC_N16
3V3	-	41	42	-	FORCE2V5_L
3V3	-	43	44	-	2V5
5V0	-	45	46	-	VREF
5V0	-	47	48	-	VccIO
VBATT	-	49	50	-	VccIO
12V0	-	51	52	-	VccIO
12V0	-	53	54	-	M12V0
PRESENCE_L	-	55	56	-	TDI
TCK	-	57	58	-	TRST
TMS	-	59	60	-	TDO

Table B.1: XRM Connector CN1, Field 1

B.2. XRM Connector CN1, Field 2

Signal	FPGA	Samtec	Samtec	FPGA	Signal
DB_N2	V39	61	62	U34	DB_N3
DB_P2	U39	63	64	V34	DB_P3
DB_N4	U38	65	66	V35	DB_N5
DB_P4	U37	67	68	W35	DB_P5
DB_N6	U33	69	70	W38	DB_N7
DB_P6	U32	71	72	V38	DB_P7
DB_N8	U41	73	74	V40	DB_P9
DB_P8	U42	75	76	W40	DB_N9
DB_P10	V33	77	78	W41	DB_N11
DB_N10	W33	79	80	V41	DB_P11
DB_N12	Y39	81	82	W42	DB_P13
DB_P12	Y40	83	84	Y42	DB_N13
DB_N14	Y35	85	86	AA39	DB_N15
DB_P14	AA35	87	88	Y38	DB_P15
DB_CC_P16	W32	89	90	AA34	SB_1
DB_CC_N16	Y33	91	92	AC38	SC_0
SA_1	R35	93	94	AD36	SC_1
SB_0	AA36	95	96	AG38	SD_0
DC_CC_P16	AD32	97	98	AB38	DC_N1
DC_CC_N16	AE32	99	100	AB37	DC_P1
DC_N0	AB36	101	102	AH34	DD_CC_P16
DC_P0	AC36	103	104	AJ35	DD_CC_N16
SD_1	AG36	105	106	AH35	SD_3
SD_2	AJ36	107	108	AF30	GCLK_M2C_N
MGTCLK_M2C_P	G10	109	110	AE30	GCLK_M2C_P
MGTCLK_M2C_N	G9	111	112	-	SDA
MGTCLK_C2M_N	-	113	114	-	SCL
MGTCLK_C2M_P	-	115	116	-	ALERT_N
MGT_C2M_P7	K3	117	118	J5	MGT_M2C_P7
MGT_C2M_N7	K4	119	120	J6	MGT_M2C_N7

Table B.2: XRM Connector CN1, Field 2

B.3. XRM Connector CN1, Field 3

Signal	FPGA	Samtec	Samtec	FPGA	Signal
DC_P2	AC41	121	122	AA42	DC_P3
DC_N2	AD41	123	124	AB42	DC_N3
DC_N4	AC33	125	126	AB39	DC_P5
DC_P4	AC34	127	128	AA40	DC_N5
DC_P6	AD42	129	130	AC40	DC_P7
DC_N6	AE42	131	132	AD40	DC_N7
DC_N8	AD33	133	134	AB41	DC_N9
DC_P8	AE33	135	136	AA41	DC_P9
DC_P10	AF42	137	138	AD38	DC_N11
DC_N10	AF41	139	140	AE38	DC_P11
DC_P12	AB32	141	142	AD37	DC_N13
DC_N12	AB33	143	144	AE37	DC_P13
DC_N14	AE39	145	146	AL42	DD_P1
DC_P14	AE40	147	148	AM42	DD_N1
DD_P0	AK38	149	150	AE35	DC_N15
DD_N0	AJ38	151	152	AE34	DC_P15
DD_P2	AJ42	153	154	AM41	DD_N3
DD_N2	AK42	155	156	AL41	DD_P3
DD_N4	AG37	157	158	AG41	DD_N5
DD_P4	AF37	159	160	AF40	DD_P5
DD_P6	AK40	161	162	AL39	DD_N7
DD_N6	AL40	163	164	AK39	DD_P7
DD_N8	AF36	165	166	AH41	DD_N9
DD_P8	AF35	167	168	AG42	DD_P9
DD_N10	AJ40	169	170	AJ41	DD_N11
DD_P10	AH39	171	172	AH40	DD_P11
DD_N12	AF34	173	174	AG39	DD_N13
DD_P12	AG34	175	176	AF39	DD_P13
DD_N14	AG33	177	178	AK37	DD_N15
DD_P14	AF32	179	180	AJ37	DD_P15

Table B.3: XRM Connector CN1, Field 3

B.4. XRM Connector J3

Signal	FPGA	Samtec Pin	Samtec Pin	FPGA	Signal
MGT_C2M_P0	J1	1	2	H7	MGT_M2C_P0
MGT_C2M_N0	J2	3	4	H8	MGT_M2C_N0
MGT_C2M_P1	H3	5	6	G5	MGT_M2C_P1
MGT_C2M_N1	H4	7	8	G6	MGT_M2C_N1
MGT_C2M_P4	N1	9	10	P7	MGT_M2C_P4
MGT_C2M_N4	N2	11	12	P8	MGT_M2C_N4
MGT_C2M_P5	M3	13	14	N5	MGT_M2C_P5
MGT_C2M_N5	M4	15	16	N6	MGT_M2C_N5
MGT_C2M_P2	G1	17	18	F7	MGT_M2C_P2
MGT_C2M_N2	G2	19	20	F8	MGT_M2C_N2
MGT_C2M_P3	F3	21	22	E5	MGT_M2C_P3
MGT_C2M_N3	F4	23	24	E6	MGT_M2C_N3
MGT_C2M_P6	L1	25	26	L5	MGT_M2C_P6
MGT_C2M_N6	L2	27	28	L6	MGT_M2C_N6

Table B.4: XRM Connector J3

Appendix C. XRM-IO146 Pinout

The following tables detail the pin-out of the Mictor connector on the XRM-IO146 when fitted to an ADM-XRC-6TL.

Signal	FPGA	Samtec	Mictor	Mictor	Samtec	FPGA	Signal
DA_P0	N38	3	1	2	6	P40	DA_P3
DA_N0	N39	1	3	4	8	P41	DA_N3
DA_P2	U36	7	5	6	4	M38	DA_P1
DA_N2	T36	5	7	8	2	M39	DA_N1
DA_P4	L39	11	9	10	12	L41	DA_P5
DA_N4	L40	9	11	12	10	L42	DA_N5
DA_P6	T34	15	13	14	16	P42	DA_P7
DA_N6	T35	13	15	16	14	R42	DA_N7
DA_P8	R39	17	17	18	18	M41	DA_P9
DA_N8	P38	19	19	20	20	M42	DA_N9
DA_P10	N36	23	21	22	24	R40	DA_P11
DA_N10	P37	21	23	24	22	T40	DA_N11
DA_P12	T39	27	25	26	26	N40	DA_P13
DA_N12	R38	25	27	28	28	N41	DA_N13
DA_P14	M36	31	29	30	30	T41	DA_P15
DA_N14	M37	29	31	32	32	T42	DA_N15
SA_0	N35	37	33	34	38	P36	DA_CC_P16
SA_1	R35	93	35	36	40	P35	DA_CC_N16
+5V	-	-	37	38	90	AA34	SB_1

Table C.1: XRM-IO146 Pinout, pins 1 - 38

Signal	FPGA	Samtec	Mictor	Mictor	Samtec	FPGA	Signal
DB_P0	W37	35	39	40	36	W36	DB_P1
DB_N0	Y37	33	41	42	34	V36	DB_N1
DB_P2	U39	63	43	44	64	V34	DB_P3
DB_N2	V39	61	45	46	62	U34	DB_N3
DB_P4	U37	67	47	48	68	W35	DB_P5
DB_N4	U38	65	49	50	66	V35	DB_N5
DB_P6	U32	71	51	52	72	V38	DB_P7
DB_N6	U33	69	53	54	70	W38	DB_N7
DB_P8	U42	75	55	56	74	V40	DB_P9
DB_N8	U41	73	57	58	76	W40	DB_N9
DB_P10	V33	77	59	60	80	V41	DB_P11
DB_N10	W33	79	61	62	78	W41	DB_N11
DB_P12	Y40	83	63	64	82	W42	DB_P13
DB_N12	Y39	81	65	66	84	Y42	DB_N13
DB_P14	AA35	87	67	68	88	Y38	DB_P15
DB_N14	Y35	85	69	70	86	AA39	DB_N15
SD_1	AG36	105	71	72	89	W32	DB_CC_P16
SD_2	AJ36	107	73	74	91	Y33	DB_CC_N16
+5V	-	-	75	76	95	AA36	SB_0

Table C.2: XRM-IO146 Pinout, pins 39 - 76

Signal	FPGA	Samtec	Mictor	Mictor	Samtec	FPGA	Signal
DC_P0	AC36	103	77	78	100	AB37	DC_P1
DC_N0	AB36	101	79	80	98	AB38	DC_N1
DC_P2	AC41	121	81	82	122	AA42	DC_P3
DC_N2	AD41	123	83	84	124	AB42	DC_N3
DC_P4	AC34	127	85	86	126	AB39	DC_P5
DC_N4	AC33	125	87	88	128	AA40	DC_N5
DC_P6	AD42	129	89	90	130	AC40	DC_P7
DC_N6	AE42	131	91	92	132	AD40	DC_N7
DC_P8	AE33	135	93	94	136	AA41	DC_P9
DC_N8	AD33	133	95	96	134	AB41	DC_N9
DC_P10	AF42	137	97	98	140	AE38	DC_P11
DC_N10	AF41	139	99	100	138	AD38	DC_N11
DC_P12	AB32	141	101	102	144	AE37	DC_P13
DC_N12	AB33	143	103	104	142	AD37	DC_N13
DC_P14	AE40	147	105	106	152	AE34	DC_P15
DC_N14	AE39	145	107	108	150	AE35	DC_N15
SC_0	AC38	92	109	110	97	AD32	DC_CC_P16
SC_1	AD36	94	111	112	99	AE32	DC_CC_N16
+5V	-	-	113	114	-	-	+5V

Table C.3: XRM-IO146 Pinout, pins 77 - 114

Signal	FPGA	Samtec	Mictor	Mictor	Samtec	FPGA	Signal
DD_P0	AK38	149	115	116	146	AL42	DD_P1
DD_N0	AJ38	151	117	118	148	AM42	DD_N1
DD_P2	AJ42	153	119	120	156	AL41	DD_P3
DD_N2	AK42	155	121	122	154	AM41	DD_N3
DD_P4	AF37	159	123	124	160	AF40	DD_P5
DD_N4	AG37	157	125	126	158	AG41	DD_N5
DD_P6	AK40	161	127	128	164	AK39	DD_P7
DD_N6	AL40	163	129	130	162	AL39	DD_N7
DD_P8	AF35	167	131	132	168	AG42	DD_P9
DD_N8	AF36	165	133	134	166	AH41	DD_N9
DD_P10	AH39	171	135	136	172	AH40	DD_P11
DD_N10	AJ40	169	137	138	170	AJ41	DD_N11
DD_P12	AG34	175	139	140	176	AF39	DD_P13
DD_N12	AF34	173	141	142	174	AG39	DD_N13
DD_P14	AF32	179	143	144	180	AJ37	DD_P15
DD_N14	AG33	177	145	146	178	AK37	DD_N15
SD_0	AG38	96	147	148	102	AH34	DD_CC_P16
SD_3	AH35	106	149	150	104	AJ35	DD_CC_N16
+5V	-	-	151	152	-	-	+5V

Table C.4: XRM-IO146 Pinout, pins 115 - 152